

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hiroataka Akao	12/03/2009
Yuriko Kaino	12/04/2009
Takahiro Kamei	12/12/2009
Masaki Hara	12/07/2009
Kenichi Kurihara	12/04/2009
RECEIVING PARTY DATA	
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City:	Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12694342
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ATTORNEY DOCKET NUMBER:	09792909-7849
NAME OF SUBMITTER:	David R. Metzger
Total Attachments: 2	

OP \$40.00 12694342

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**PATENT
 REEL: 023852 FRAME: 0681**

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ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

FILM DEPOSITION METHOD AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan** (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 12/694,342, Filing Date: January 27, 2010

This assignment executed on the dates indicated below.

HIROTAKA AKAO

Name of first or sole inventor
TOKYO JAPAN

Residence of First or sole inventor

Hirotake Akao
Signature of first or sole inventor

Execution date of U.S. Patent Application

December 3, 2009
Date of this assignment

YURIKO KAINO

Name of second inventor
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Residence of second inventor

Yuriko Kaino
Signature of second inventor

Execution date of U.S. Patent Application

December 4, 2009
Date of this assignment

TAKAHIRO KAMEI

Name of third inventor
KANAGAWA JAPAN

Residence of third inventor

Takahiro Kamei
Signature of third inventor

Execution date of U.S. Patent Application

December 12, 2009
Date of this assignment

PATENT

REEL: 023852 FRAME: 0683

ADDITIONAL INVENTOR(S)

MASAKI HARA

Name of fourth inventor
KANAGAWA JAPAN

Residence of fourth inventor

Masaki Hara
Signature of fourth inventor

Execution date of U.S. Patent Application

December 7, 2009
Date of this assignment

KENICHI KURIHARA

Name of fifth inventor
KANAGAWA JAPAN

Residence of fifth inventor

Kenichi Kurihara
Signature of fifth inventor

Execution date of U.S. Patent Application

Dec 4, 2009
Date of this assignment

Name of sixth inventor

Residence of sixth inventor

Signature of sixth inventor

Execution date of U.S. Patent Application

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Name of ninth inventor

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Execution date of U.S. Patent Application

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